



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC100N04S6N028	Issued	12. May 2021
MA#	MA001701708		
Package	PG-TDSON-8-33	Weight*	111.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.443	0.40	0.40	3972	3972
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142	
	non noble metal	iron	7439-89-6	0.053	0.05		475	
	non noble metal	copper	7440-50-8	52.842	47.42	47.48	474186	474803
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	398	398
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		690	
	plastics	epoxy resin	-	6.073	5.45		54495	
	inorganic material	silicondioxide	60676-86-0	32.286	28.97	34.49	289721	344906
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14123	14123
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1877	1877
solder	non noble metal	tin	7440-31-5	0.013	0.01		119	
	noble metal	silver	7440-22-4	0.017	0.01		148	
	non noble metal	lead	7439-92-1	0.632	0.57	0.59	5671	5938
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2778	2782
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.10	15.12	151005	151201
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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